



FDH50N50_F133 / FDA50N50

500V N-Channel MOSFET

Features

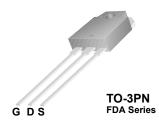
- 48A, 500V, $R_{DS(on)} = 0.105\Omega$ @ $V_{GS} = 10 \text{ V}$
- Low gate charge (typical 105 nC)
- Low C_{rss} (typical 45 pF)
- · Fast switching
- 100% avalanche tested
- · Improved dv/dt capability

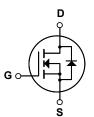
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.







Absolute Maximum Ratings

Symbol	Parameter		FDH50N50_F133/FDA50N50	Unit	
V_{DSS}	Drain-Source Voltage		500	V	
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		48 30.8	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	192	Α
V _{GSS}	Gate-Source voltage		±20	V	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	1868	mJ
I _{AR}	Avalanche Current		(Note 1)	48	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	62.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		20	V/ns	
P _D	Power Dissipation (T _C = 25°C) - Derate above 25°C		625 5	W W/°C	
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Min.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.2	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDH50N50_F133	FDH50N50_F133	TO-247	-	-	30
FDA50N50	FDA50N50	TO-3PN	-	-	30

Electrical Characteristics $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Тур.	Max	Units
Off Charac	Off Characteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	500			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.5		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V V _{DS} = 400V, T _C = 125°C			25 250	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20V, V _{DS} = 0V			-100	nA
On Charac	teristics				•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 24A		0.089	0.105	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 48A (Note 4)		20		S
Dynamic C	haracteristics				•	
C _{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$		4979	6460	pF
C _{oss}	Output Capacitance	f = 1.0MHz		760	1000	pF
C _{rss}	Reverse Transfer Capacitance			50	65	pF
C _{oss}	Output Capacitance	V _{DS} = 400V, V _{GS} = 0V, f = 1.0MHz		161		pF
C _{oss} eff.	Effective Output Capacitance	V _{DS} = 0V to 400V, V _{GS} = 0V		342		pF
Switching	Characteristics		•			
t _{d(on)}	Turn-On Delay Time	V _{DD} = 250V, I _D = 48A		105	220	ns
t _r	Turn-On Rise Time	$R_{G} = 25\Omega$		360	730	ns
t _{d(off)}	Turn-Off Delay Time			225	460	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		230	470	ns
Qg	Total Gate Charge	V _{DS} = 400V, I _D = 48A		105	137	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10V		33		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		45		nC
Drain-Sour	rce Diode Characteristics and Maximum	n Ratings	l	I	l	
I _S Maximum Continuous Drain-Source Diode Forward Current					48	Α
I _{SM} Maximum Pulsed Drain-Source Diode Fo		orward Current			192	Α
V_{SD}	Drain-Source Diode Forward Voltage V _{GS} = 0V, I _S = 48A				1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 48A		580		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$ (Note 4)		10		μС

NOTES:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 1.46mH, I $_{AS}$ = 48A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C
- 3. $I_{SD} \leq$ 48A, di/dt \leq 200A/ μ s, $V_{DD} \leq$ BV $_{DSS}$, Starting T $_{J}$ = 25°C
- 4. Pulse Test: Pulse width $\leq 300 \mu s,$ Duty Cycle $\leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

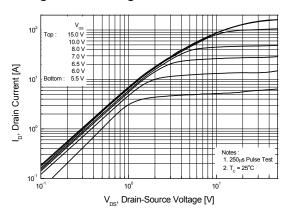


Figure 2. Transfer Characteristics

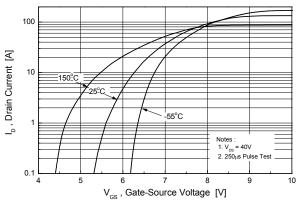


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

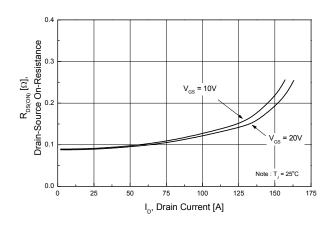


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

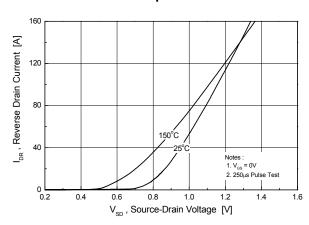


Figure 5. Capacitance Characteristics

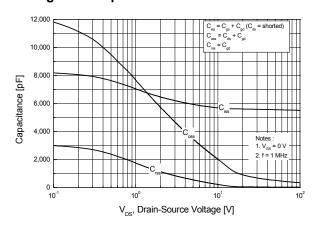
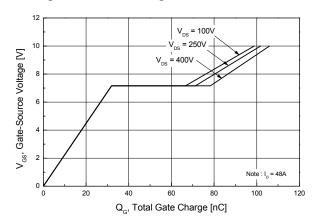


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

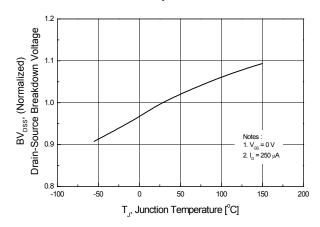


Figure 8. On-Resistance Variation vs. Temperature

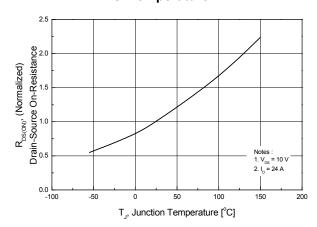


Figure 9. Maximum Safe Operating Area

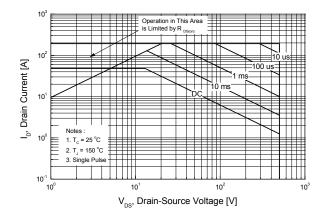


Figure 10. Maximum Drain Current vs. Case Temperature

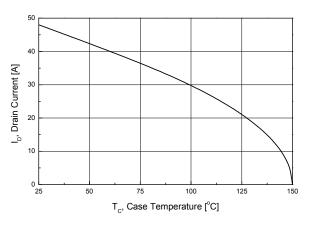


Figure 11. Typical Drain Current Slope vs. Gate Resistance

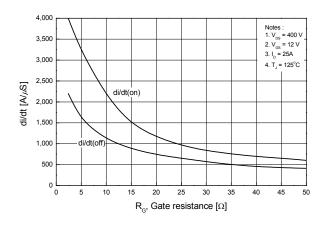
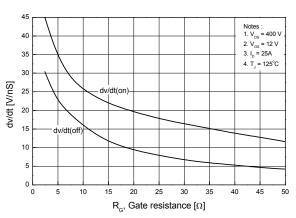


Figure 12. Typical Drain-Source Voltage Slope vs. Gate Resistance



Typical Performance Characteristics (Continued)

Figure 13. Typical Switching Losses vs. Gate Resistance

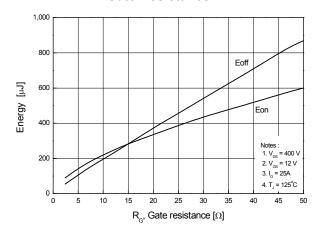


Figure 14. Unclamped Inductive Switching Capability

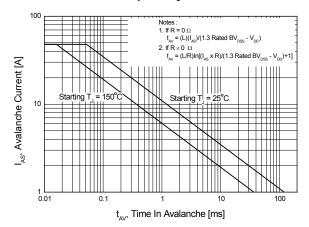
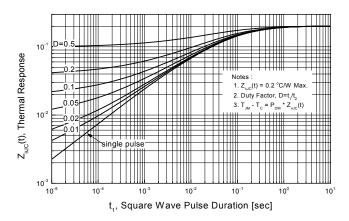
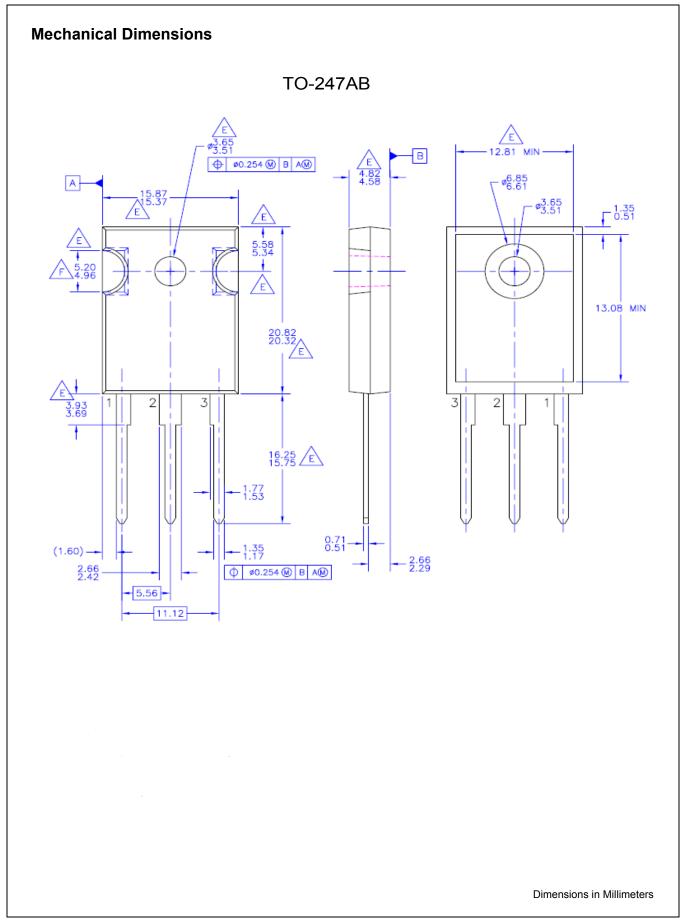


Figure 15. Transient Thermal Resistance Curve





Mechanical Dimensions TO-3PN 5.00 4.60 ø3.30 3.10 15.80 15.40 1.65 1.45 (R0.50) -5.20 4.80 20.10 19.70 18.90 18.50 3.70 3.30 (1.85)2.20 1.80 2.60 2.20 3,20 2,80 20.30 19.70 **⊕** Ø0.55**⊚** 1.20 0.80 1 3 5.45 5.45 (R0,50) Dimensions in Millimeters





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Rev. 161